

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-7 (Canceled).

8. (New) A method of manufacturing a silicon wafer, the method comprising:
polishing side faces of a silicon block used for manufacturing the silicon wafer;
and
slicing the silicon block.

9. (New) The method of claim 8, wherein the polished side faces of the silicon block have a surface roughness R_y of $8\mu\text{m}$ or less.

10. (New) A method of manufacturing a silicon inclusive wafer, the method comprising:
polishing side faces of a block comprising silicon, which is used for
manufacturing the silicon inclusive wafer; and
slicing the block.

11. (New) The method of claim 10, wherein at least one polished side face of the block has a surface roughness R_y of $8\mu\text{m}$ or less.